



TE Internal #: 2-2013022-1
Double Data Rate (DDR) 3, 4 mm [.157 in] Stack Height, Right Angle
Module Orientation, 204 Position, .6 mm [.024 in] Centerline, SO
DIMM Sockets
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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: Double Data Rate (DDR) 3
Stack Height: 4 mm [.157 in]
Module Orientation: Right Angle
Number of Positions: 204
Centerline (Pitch): .6 mm [.024 in]

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Cable-to-Board
DRAM Type	Double Data Rate (DDR) 3

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	204

Electrical Characteristics

DRAM Voltage	1.5 V
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Signal Characteristics

SGRAM Voltage	1.5 V
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Body Features

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Latch Plating Material	Tin
Latch Material	Stainless Steel
Module Key Type	SGRAM
Ejector Type	Locking
Ejector Location	Both Ends
Connector Profile	Standard

Contact Features

Contact Current Rating (Max)	.5 A
Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Gold Flash
Contact Mating Area Plating Material	Gold Flash

Termination Features

Insertion Style	Cam-In
Termination Method to PCB	Surface Mount

Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention Type	Solder Tail
Mating Alignment Type	Standard Keying
PCB Mount Retention	With

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.6 mm[.024 in]

Dimensions

Stack Height	4 mm[.157 in]
Row-to-Row Spacing	8.2 mm[.322 in]

Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards



UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	200
Packaging Method	Emboss on Reel

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts





Customers Also Bought



TE Part #1-1469373-1
ATCA GUIDE MODULE RA FEMALE



TE Part #5353928-1
Std USB Type A, R/A, SMT, Offset, Panel



TE Part #1888968-1
Cage Assy PCI Hsink QSFP Behind Bezel



TE Part #5-147279-9
16 MODII HDR DR SFMT B/A T&R L



TE Part #1-178296-3
DYNAMIC D3100 HDR ASSY 6P H K/X



TE Part #2-2013290-1
EMBOSS TAPE DDR3 204P 5.2H RVS



TE Part #2007464-1
SFP+ 1x1 Cage Assy, PF,with Heatsink



TE Part #5-1393789-0
V23079G2002B301



TE Part #1888968-2
Cage Assy SAN Hsink QSFP Behind Bezel



TE Part #2132186-2
EMI Gasket, QSFP/XFP 1x1

Documents

Product Drawings
EMBOSS TAPE DDR3 204P 4H STD
English

CAD Files
Customer View Model
ENG_CVM_CVM_2-2013022-1_B.2d_dxf.zip
English

3D PDF
3D
Customer View Model
ENG_CVM_CVM_2-2013022-1_B.3d_igs.zip
English

Customer View Model
ENG_CVM_CVM_2-2013022-1_B.3d_stp.zip
English

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Datasheets & Catalog Pages

DDR3 DIMM Sockets Flyer 6-1773454-7 05/09

English

6-1773457-3_DDR3_DIMM_SOCKETS

Product Specifications

Product Specification

English